

4N25
4N37

4N26
H11A1

4N27
H11A2

4N28
H11A3

4N35
H11A4

4N36
H11A5

DESCRIPTION

The general purpose optocouplers consist of a gallium arsenide infrared emitting diode driving a silicon phototransistor in a 6-pin dual in-line package.

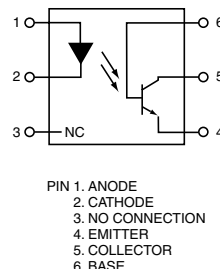
FEATURES

- UL recognized (File # E90700)
- VDE recognized (File # 94766)
 - Add option V for white package (e.g., 4N25V-M)
 - Add option 300 for black package (e.g., 4N25.300)
- Also available in white package by specifying -M suffix, eg. 4N25-M except H11A2, H11A4 and H11A5

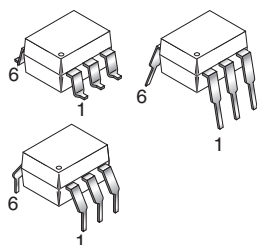
APPLICATIONS

- Power supply regulators
- Digital logic inputs
- Microprocessor inputs

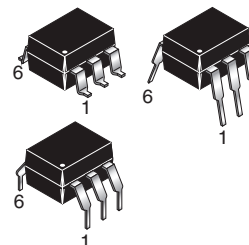
SCHEMATIC



WHITE PACKAGE (-M SUFFIX)



BLACK PACKAGE (NO -M SUFFIX)



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Units
TOTAL DEVICE			
Storage Temperature	T _{STG}	-55 to +150	°C
Operating Temperature	T _{OPR}	-55 to +100	°C
Lead Solder Temperature	T _{SOL}	260 for 10 sec	°C
Total Device Power Dissipation @ T _A = 25°C	P _D	250	mW
Derate above 25°C		3.3 (non-M), 2.94 (-M)	
EMITTER			
DC/Average Forward Input Current	I _F	100 (non-M), 60 (-M)	mA
Reverse Input Voltage	V _R	6	V
Forward Current - Peak (300μs, 2% Duty Cycle)	I _F (pk)	3	A
LED Power Dissipation @ T _A = 25°C	P _D	150 (non-M), 120 (-M)	mW
Derate above 25°C		2.0 (non-M), 1.41 (-M)	mW/°C
DETECTOR			
Collector-Emitter Voltage	V _{CEO}	30	V
Collector-Base Voltage	V _{CBO}	70	V
Emitter-Collector Voltage	V _{ECO}	7	V
Detector Power Dissipation @ T _A = 25°C	P _D	150	mW
Derate above 25°C		2.0 (non-M), 1.76 (-M)	mW/°C

4N25
4N37

4N26
H11A1

4N27
H11A2

4N28
H11A3

4N35
H11A4

4N36
H11A5

ELECTRICAL CHARACTERISTICS (T_A = 25°C Unless otherwise specified.)

INDIVIDUAL COMPONENT CHARACTERISTICS

Parameter	Test Conditions	Symbol	Min	Typ**	Max	Unit
EMITTER						
Input Forward Voltage	(I _F = 10 mA)	V _F		1.18	1.50	V
Reverse Leakage Current	(V _R = 6.0 V)	I _R		0.001	10	μA
DETECTOR						
Collector-Emitter Breakdown Voltage	(I _C = 1.0 mA, I _F = 0)	BV _{CEO}	30	100		V
Collector-Base Breakdown Voltage	(I _C = 100 μA, I _F = 0)	BV _{CBO}	70	120		V
Emitter-Collector Breakdown Voltage	(I _E = 100 μA, I _F = 0)	BV _{ECO}	7	10		V
Collector-Emitter Dark Current	(V _{CE} = 10 V, I _F = 0)	I _{CEO}		1	50	nA
Collector-Base Dark Current	(V _{CB} = 10 V)	I _{CBO}			20	nA
Capacitance	(V _{CE} = 0 V, f = 1 MHz)	C _{CE}		8		pF

ISOLATION CHARACTERISTICS

Characteristic	Test Conditions	Symbol	Min	Typ**	Max	Units
Input-Output Isolation Voltage	(Non-'M', Black Package) (f = 60 Hz, t = 1 min)	V _{ISO}	5300			Vac(rms)*
	('M', White Package) (f = 60 Hz, t = 1 sec)		7500			Vac(pk)
Isolation Resistance	(V _{I-O} = 500 VDC)	R _{ISO}	10 ¹¹			Ω
Isolation Capacitance	(V _{I-O} = ∅, f = 1 MHz)	C _{ISO}		0.5		pF
	('M' White Package)			0.2	2	pF

Note

* 5300 Vac(rms) for 1 minute equates to approximately 9000 Vac (pk) for 1 second

** Typical values at T_A = 25°C

**4N25
4N37**

**4N26
H11A1**

**4N27
H11A2**

**4N28
H11A3**

**4N35
H11A4**

**4N36
H11A5**

TRANSFER CHARACTERISTICS ($T_A = 25^\circ\text{C}$ Unless otherwise specified.)

DC Characteristic	Test Conditions	Symbol	Device	Min	Typ**	Max	Unit
Current Transfer Ratio, Collector to Emitter	(I _F = 10 mA, V _{CE} = 10 V)	CTR	4N35	100			%
			4N36				
			4N37				
			H11A1	50			
			H11A5	30			
			4N25	20			
	4N26						
	H11A2						
	H11A3		10				
	4N27						
4N28							
H11A4	40						
4N35							
4N36							
4N37	40						
4N35							
4N36							
4N37							
(I _F = 10 mA, V _{CE} = 10 V, T _A = -55°C)							
(I _F = 10 mA, V _{CE} = 10 V, T _A = +100°C)							
Collector-Emitter Saturation Voltage	(I _C = 2 mA, I _F = 50 mA)	V _{CE (SAT)}	4N25			0.5	V
	(I _C = 0.5 mA, I _F = 10 mA)		4N26				
			4N27				
			4N28				
			4N35		0.3		
			4N36				
4N37							
H11A1		0.4					
H11A2							
H11A3							
H11A4							
H11A5							
AC Characteristic							
Non-Saturated Turn-on Time	(I _F = 10 mA, V _{CC} = 10 V, R _L = 100Ω) (Fig.20)	T _{ON}	4N25		2		μs
		4N26					
		4N27					
		4N28					
		H11A1					
		H11A2					
		H11A3					
		H11A4					
		H11A5					

** Typical values at $T_A = 25^\circ\text{C}$

4N25
4N37

4N26
H11A1

4N27
H11A2

4N28
H11A3

4N35
H11A4

4N36
H11A5

TRANSFER CHARACTERISTICS (Cont.)

AC Characteristic	Test Conditions	Symbol	Device	Min	Typ**	Max	Unit
Non Saturated Turn-on Time	($I_C = 2 \text{ mA}$, $V_{CC} = 10 \text{ V}$, $R_L = 100\Omega$) (Fig.20)	T_{ON}	4N35 4N36 4N37		2	10	μs
Turn-off Time	($I_F = 10 \text{ mA}$, $V_{CC} = 10 \text{ V}$, $R_L = 100\Omega$) (Fig.20)	T_{OFF}	4N25 4N26 4N27 4N28 H11A1 H11A2 H11A3 H11A4 H11A5		2		μs
	($I_C = 2 \text{ mA}$, $V_{CC} = 10 \text{ V}$, $R_L = 100\Omega$) (Fig.20)		4N35 4N36 4N37		2	10	

** Typical values at $T_A = 25^\circ\text{C}$

4N25
4N37

4N26
H11A1

4N27
H11A2

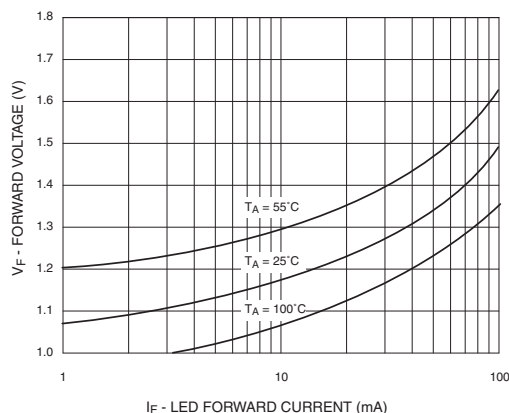
4N28
H11A3

4N35
H11A4

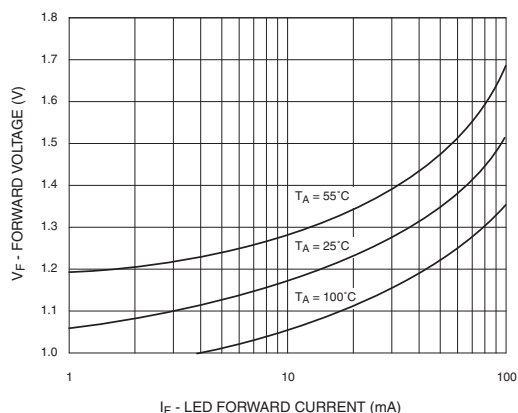
4N36
H11A5

TYPICAL PERFORMANCE CURVES

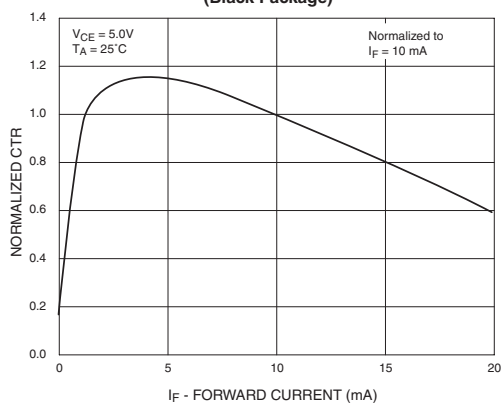
**Fig. 1 LED Forward Voltage vs. Forward Current
(Black Package)**



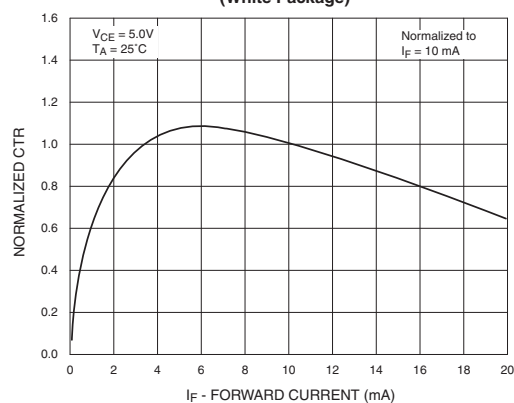
**Fig. 2 LED Forward Voltage vs. Forward Current
(White Package)**



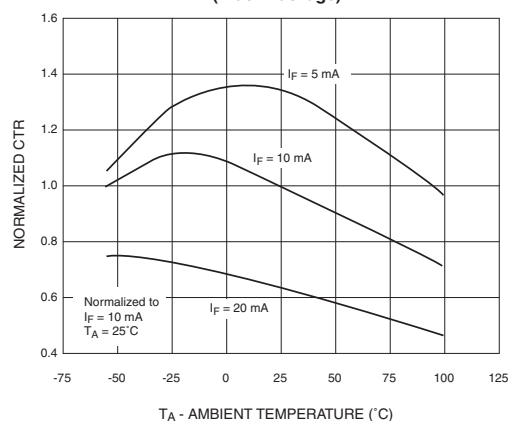
**Fig.3 Normalized CTR vs. Forward Current
(Black Package)**



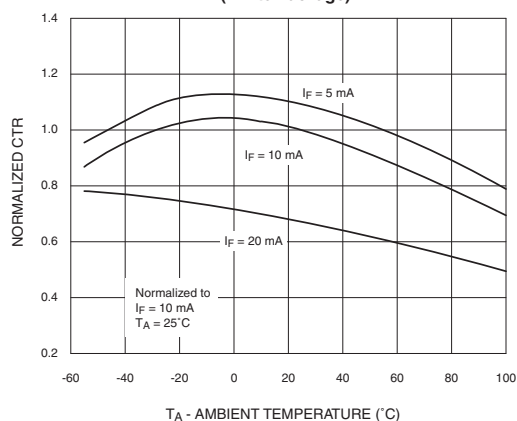
**Fig.4 Normalized CTR vs. Forward Current
(White Package)**



**Fig. 5 Normalized CTR vs. Ambient Temperature
(Black Package)**



**Fig. 6 Normalized CTR vs. Ambient Temperature
(White Package)**



4N25
4N37

4N26
H11A1

4N27
H11A2

4N28
H11A3

4N35
H11A4

4N36
H11A5

Fig. 7 CTR vs. RBE (Unsaturated)
(Black Package)

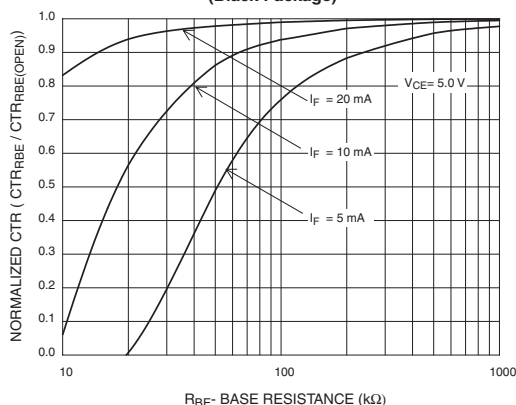


Fig. 8 CTR vs. RBE (Unsaturated)
(White Package)

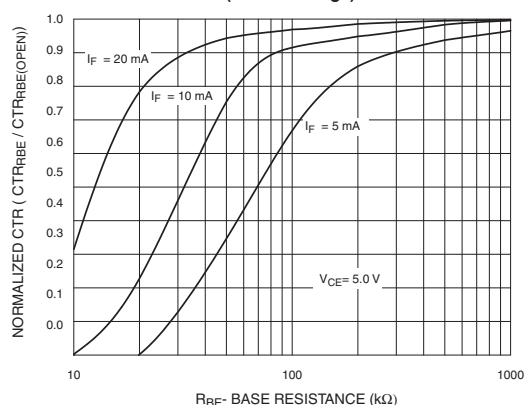


Fig. 9 CTR vs. RBE (Saturated)
(Black Package)

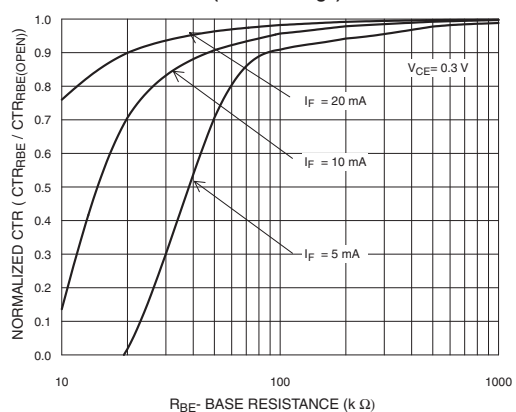


Fig. 10 CTR vs. RBE (Saturated)
(White Package)

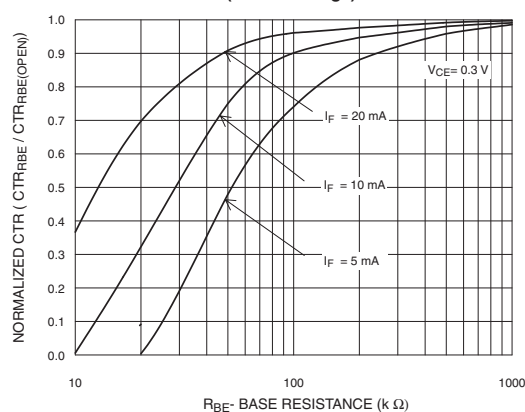


Fig. 11 Collector-Emitter Saturation Voltage vs. Collector Current
(Black Package)

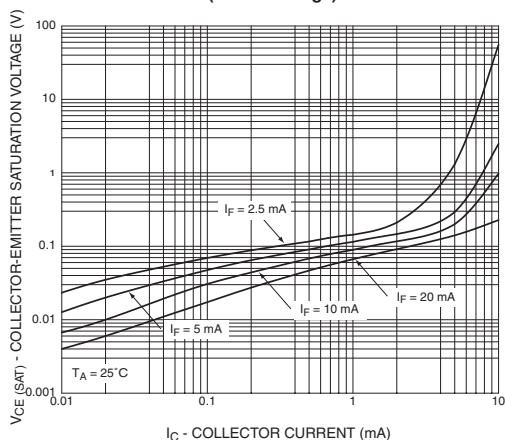
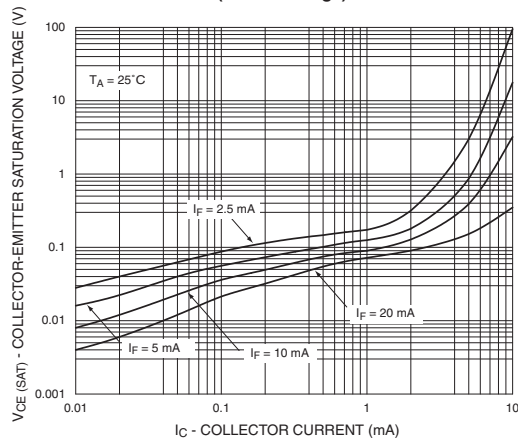


Fig. 12 Collector-Emitter Saturation Voltage vs. Collector Current
(White Package)



4N25
4N37

4N26
H11A1

4N27
H11A2

4N28
H11A3

4N35
H11A4

4N36
H11A5

Fig. 13 Switching Speed vs. Load Resistor
(Black Package)

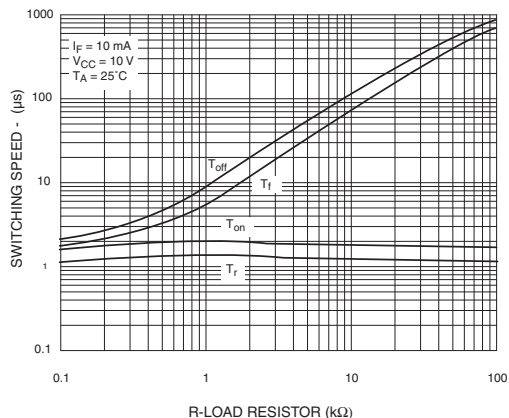


Fig. 14 Switching Speed vs. Load Resistor
(White Package)

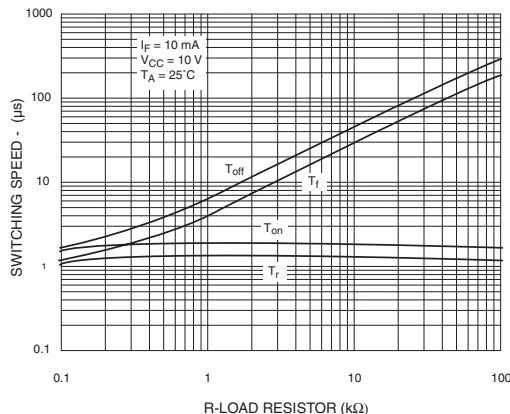


Fig. 15 Normalized t_{on} vs. R_{BE}
(Black Package)

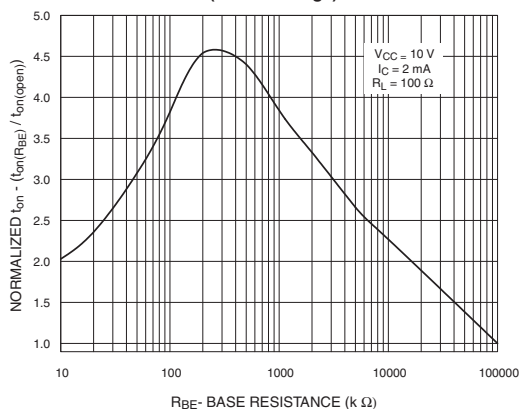


Fig. 16 Normalized t_{on} vs. R_{BE}
(White Package)

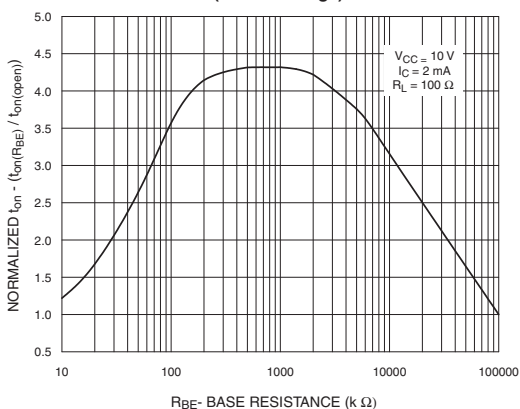


Fig. 17 Normalized t_{off} vs. R_{BE}
(Black Package)

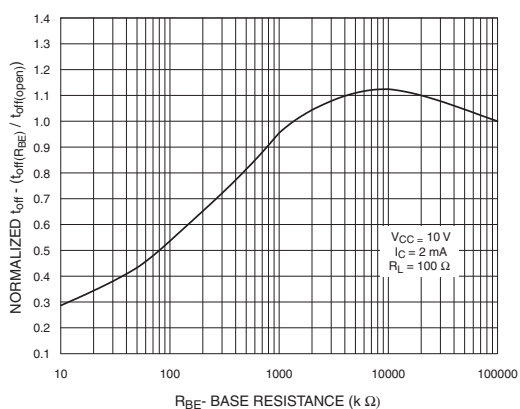
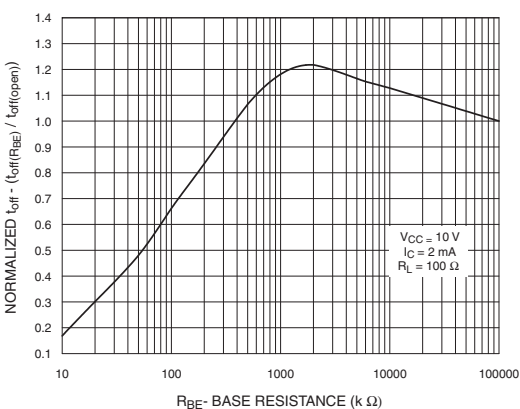


Fig. 18 Normalized t_{off} vs. R_{BE}
(White Package)



4N25
4N37

4N26
H11A1

4N27
H11A2

4N28
H11A3

4N35
H11A4

4N36
H11A5

Fig. 19 Dark Current vs. Ambient Temperature

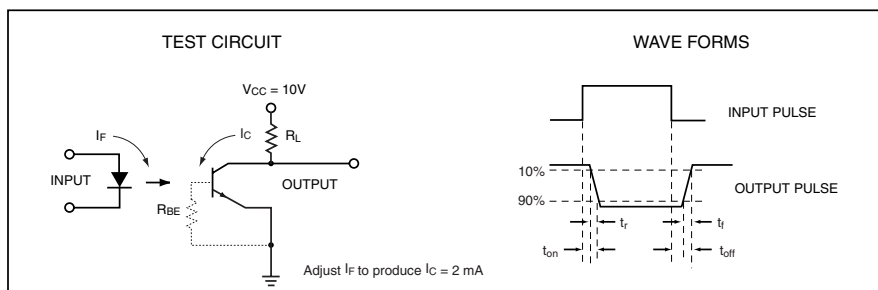
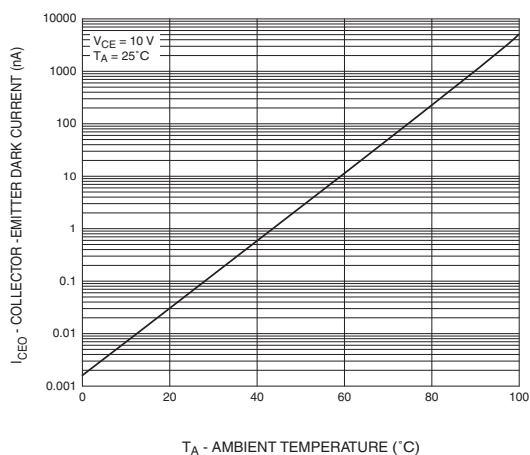


Figure 20. Switching Time Test Circuit and Waveforms

4N25
4N37

4N26
H11A1

4N27
H11A2

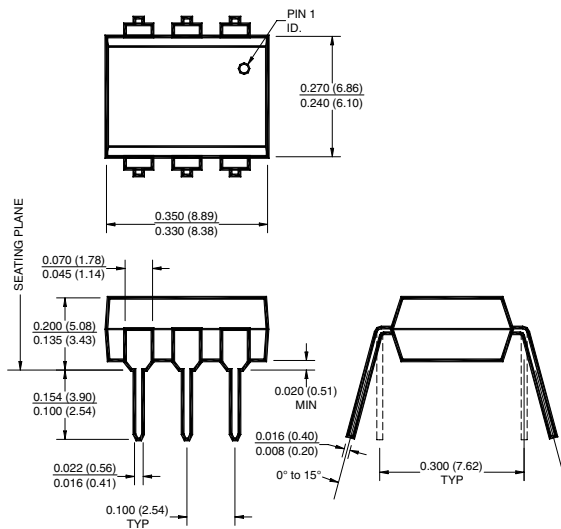
4N28
H11A3

4N35
H11A4

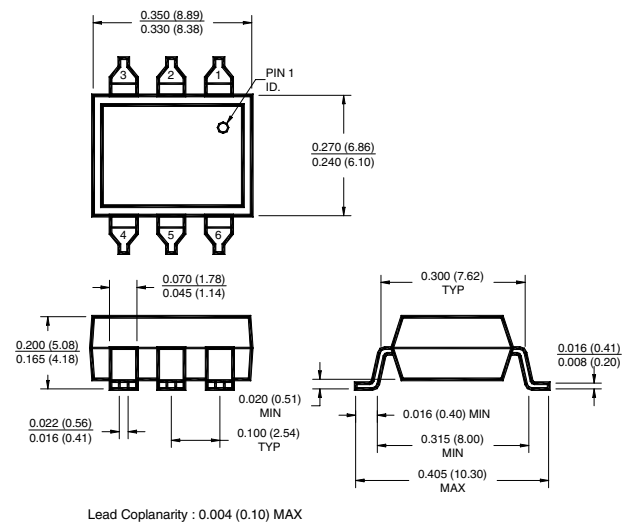
4N36
H11A5

Black Package (No -M Suffix)

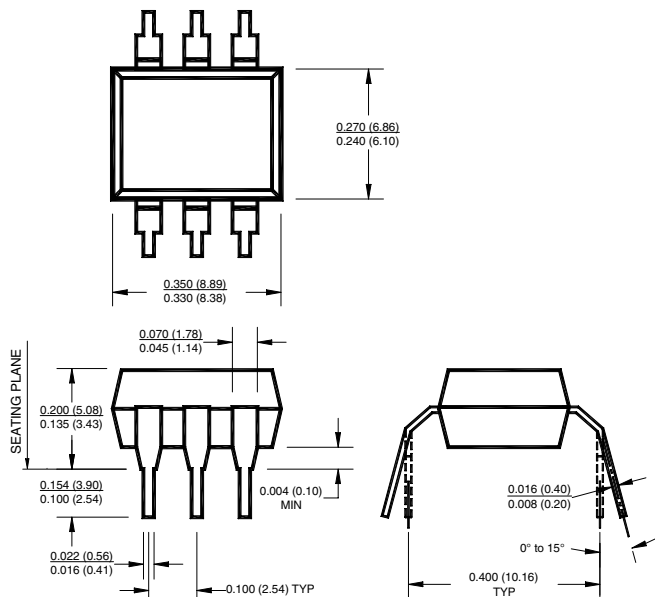
Package Dimensions (Through Hole)



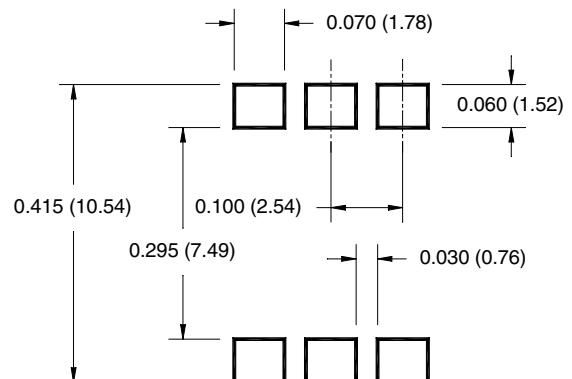
Package Dimensions (Surface Mount)



Package Dimensions (0.4" Lead Spacing)



Recommended Pad Layout for Surface Mount Leadform



NOTE

All dimensions are in inches (millimeters)

4N25
4N37

4N26
H11A1

4N27
H11A2

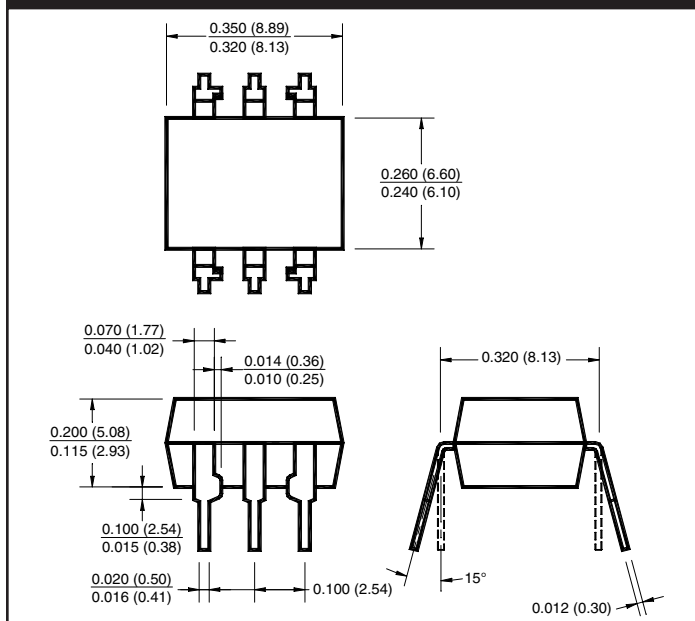
4N28
H11A3

4N35
H11A4

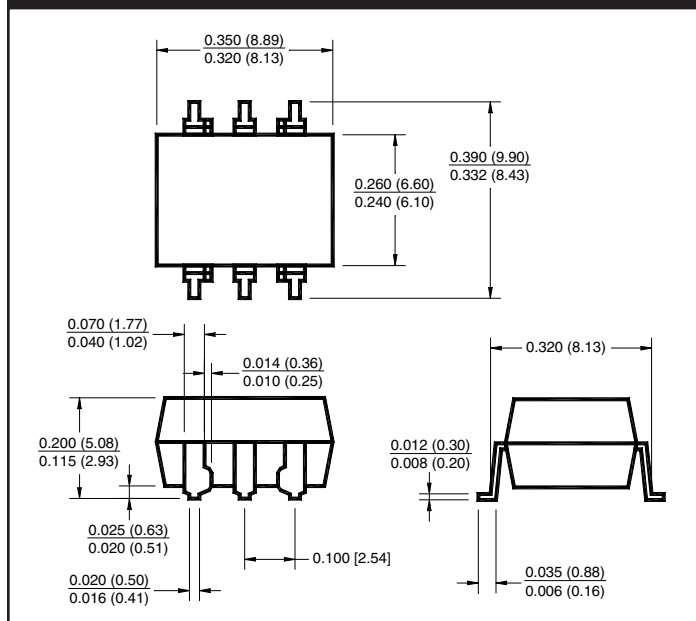
4N36
H11A5

White Package (-M Suffix)

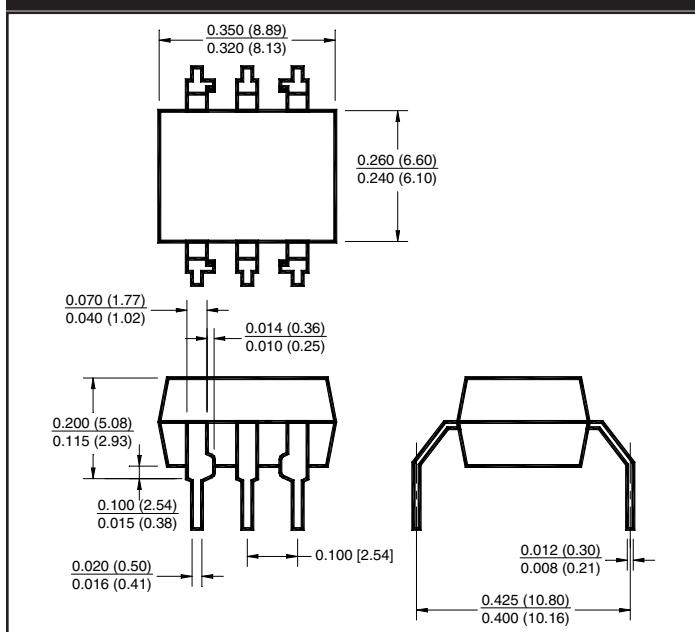
Package Dimensions (Through Hole)



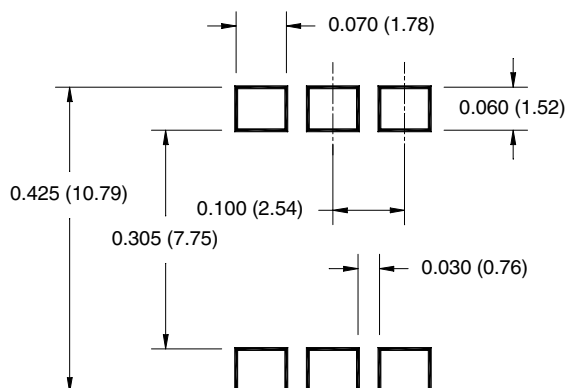
Package Dimensions (Surface Mount)



Package Dimensions (0.4" Lead Spacing)



Recommended Pad Layout for Surface Mount Leadform



NOTE

All dimensions are in inches (millimeters)

4N25
4N37

4N26
H11A1

4N27
H11A2

4N28
H11A3

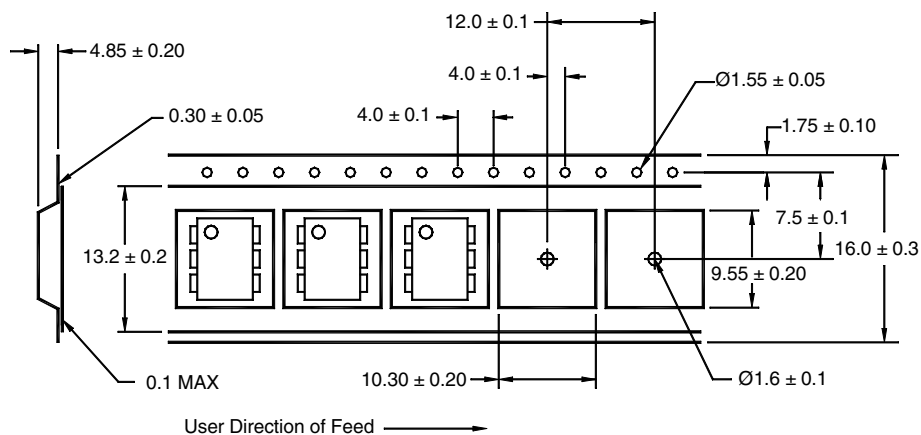
4N35
H11A4

4N36
H11A5

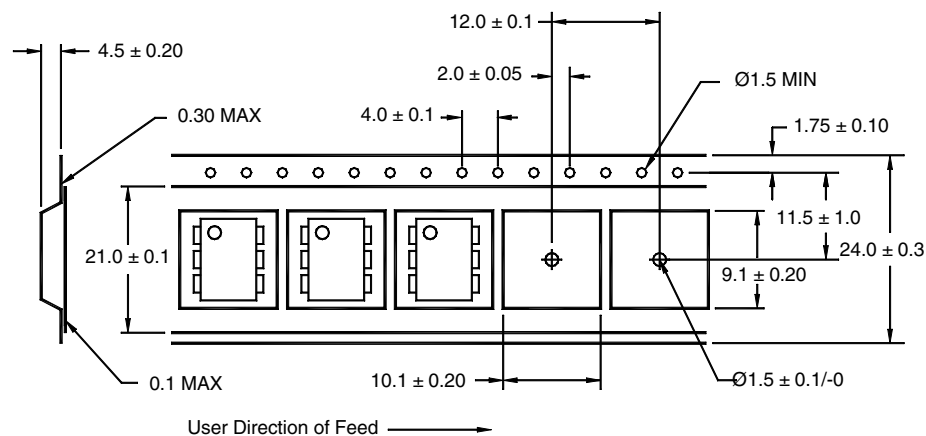
ORDERING INFORMATION

Order Entry Identifier		
Black Package (No Suffix)	White Package (-m Suffix)	Option
.S	S	Surface Mount Lead Bend
.SD	SR2	Surface Mount; Tape and reel
.W	T	0.4" Lead Spacing
.300	V	VDE 0884
.300W	TV	VDE 0884, 0.4" Lead Spacing
.3S	SV	VDE 0884, Surface Mount
.3SD	SR2V	VDE 0884, Surface Mount, Tape & Reel

QT Carrier Tape Specifications (“D” Taping Orientation) (Black Package, No Suffix)



QT Carrier Tape Specifications (“D” Taping Orientation) (White Package, -M Suffix)



4N25
4N37

4N26
H11A1

4N27
H11A2

4N28
H11A3

4N35
H11A4

4N36
H11A5

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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.